This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

31. (Currently Amended) A method for preparing an optical substrate coated with a water-repellent coating, comprising

a) mixing an electrically conductive or semiconductive support material comprising carbon; a conductive metal oxide, carbide, nitride or silicide; a metal powder and a non-conductive material; or a mixture thereof with a binder and subjecting the mixture to compression molding to form a compression molding,

b) sintering the compression molding at from 1100 to 1500°C in air to form a porous molding,

c) impregnating the molding with an organosilicon compound,

d) ageing the impregnated molding, and,

e) in the presence of an optical substrate, subjecting the aged impregnated molding under vacuum ~~to treatment in an electron beam evaporator, or subjecting the aged impregnated molding under vacuum~~ to vaporization at about 300 to 500°C,

whereby said impregnated organosilicon compound is vaporized and deposited upon the optical substrate.

32. (Currently Amended) The method of claim 31, wherein said aged

impregnated molding is subjected to vaporization ~~treatment~~ in an electron beam evaporator.

33. (Currently Amended) The method of claim 31, wherein said aged impregnated molding is subjected to vaporization by heating ~~at about 300 to 500°C~~.

34. (Previously Presented) An optical substrate coated with a water-repellent coating, prepared by the method of claim 31.

35. (Currently Amended) A method for preparing an optical substrate coated with a water-repellent coating, comprising subjecting, in the presence of an optical substrate, a porous electrically conductive molding which is impregnated with an organosilicon compound to treatment under vacuum ~~in an electron beam evaporator, or subjecting said impregnated molding under vacuum~~ to vaporization at about 300 to 500°C, thereby vaporizing said organosilicon compound and depositing it upon the optical substrate,

wherein said porous electrically conductive molding comprises carbon; a conductive metal oxide, carbide, nitride or silicide; a metal powder and a non-conductive material; or a mixture thereof.

36. (Currently Amended) The method of claim 35, wherein said impregnated molding is subjected to vaporization ~~treatment~~ in an electron beam evaporator.

37. (Currently Amended) The method of claim 35, wherein said impregnated molding

is subjected to vaporization by heating ~~at about 300 to 500°C~~.

38. (Previously Presented) An optical substrate coated with a water-repellent coating, prepared by the method of claim 35.

39. (Currently Amended) A method for preparing an optical substrate coated with a water-repellent coating, comprising subjecting, in the presence of an optical substrate, a porous electrically conductive molding which is impregnated with an organosilicon compound to treatment under vacuum ~~in an electron beam evaporator, or subjecting said impregnated molding under vacuum~~ to vaporization at about 300 to 500°C, thereby vaporizing the organosilicon compound and depositing it upon the optical substrate,

wherein said impregnated molding is obtainable by ageing a sintered compression molding which is impregnated with an organosilicon compound,

wherein said electrically conductive molding comprises carbon;

a conductive metal oxide, carbide, nitride or silicide; a metal powder and a non-conductive material; or a mixture thereof.

40. (Currently Amended) The method of claim 39, wherein said impregnated molding is subjected to vaporization ~~treatment~~ in an electron beam evaporator.

41. (Currently Amended) The method of claim 39, wherein said impregnated molding is subjected to vaporization by heating ~~at about 300 to 500°C~~.

42. (Previously Presented) An optical substrate coated with a water-repellent coating, prepared by the method of claim 39.

43. (Previously Presented) The optical substrate of claim 42, wherein said organosilicon compound is of formula I

C_nF_{2n+1}-$(CH_2)_m$-$Si(R^1R^2R^3)$ (I)

wherein

R^1 is an alkoxy of 1 to 3 a carbon atoms or C_nF_{2n+1}-$(CH_2)_m$-$Si(R^2R^3)$-O-,

R^2 and R^3 are each independently alkyl or alkoxy of 1 to 3 carbon atoms,

n is 1 to 12 and

m is 1 to 6.

44. (Previously Presented) The optical substrate of claim 42, wherein said conductive metal oxide is indium oxide or tin dioxide which is optionally doped with antimony, fluorine, phosphorus, niobium or tantalum,

said metal carbide is titanium carbide, chromium carbide or tungsten carbide,

said metal nitride is chromium nitride or tungsten nitride,

said metal silicide is molybdenum silicide, titanium silicide, or chromium silicide,

said metal powder is titanium, zirconium, silicon, chromium, nickel or iron, and/or

said non-conductive material is silicon oxide, aluminum oxide, zirconium oxide, aluminum silicate or a mixture thereof.

45. (Previously Presented) The optical substrate of claim 42, wherein said organosilicon is triethoxy (3,3,4,4,5,5,6,6,7,7,7-undecafluoroheptyl)silane, triethoxy (3,3,4,4,5,5,6,6,7,7,8,8,8-tridecafluorooctyl)silane, triethoxy (3,3,4,4,5,5,6,6,7,7,8,8,9,9,10,10,10-heptadecafluorodecyl)silane, diethoxymethyl (3,3,4,4,5,5,6,6,7,7,8,8,9,9,10,10,10-heptadecafluorodecyl)silane, or bis[ethoxymethyl(3,3,4,4,5,5,6,6,7,7,8,8,8-tridecafluorooctyl) silyl ether.

46. (Previously Presented) The optical substrate of claim 42, wherein said electrically conductive molding comprises 50 to 90% by weight of an electrically non-conductive material and 10 to 50% by weight of a metal powder, or wherein said electrically conductive molding comprises 40 to 60% by weight of aluminum silicate and 20 to 60% by weight of silicon powder.

47. (Previously Presented) The optical substrate of claim 42, wherein said ageing is performed for a time sufficient to cleave said organosilicon compound.

48. (Previously Presented) The optical substrate of claim 34, wherein said binder is polyvinyl alcohol, glycerol, methylcellulose, dextrin or a wax, and the concentration of said binder in said compression molding is 1-20% by weight.

49. (Previously Presented) The optical substrate of claim 34, wherein said compression molding is in the form of a tablet which has a diameter of 10-15 mm and a height of

5-10 mm, or in the form of a granule which has a particle size of 1-4 mm, and/or wherein said porous molding has a porosity of 40-60%.

50. (Previously Presented) The optical substrate of claim 34, wherein said compression molding is heated in air at 400-600°C before sintering it at 1100-1500°C.

51. (Previously Presented) The optical substrate of claim 42, wherein said electrically conductive molding comprises an electrically conductive material with the exception of a metal, or a mixture of an electrically conductive material and an electrically non-conductive material.

52. (Previously Presented) The optical substrate of claim 42, wherein said vacuum is 10^{5} - 10^{-3} mbar.

Please add the following new claims:

--53. (New) The method of claim 33, wherein the heating is executed directly by the passage of current.

54. (New) The method of claim 37, wherein the heating is executed directly by the passage of current.

55. (New) The method of claim 41, wherein the heating is executed directly by the passage of current.--